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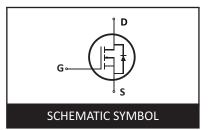
## **N-CHANNEL POWER MOSFET**

#### DESCRIPTION

This power MOSFET is produced with advanced VDMOS technology of Semiwill. This technology enable power MOSFET to have better characteristics , such as fast switching time, low on resistance , low gate charge and especially excellent avalanche characteristics . This power MOSFET is usually used at high efficient DC to DC converter block, high efficiency switch mode power supplies, power factor correction, electronic lamp ballast based on half bridge.

#### FEATURES

- High ruggedness
- R<sub>DS(ON)</sub>(Max. 0.55Ω)@V<sub>GS</sub>=10V
- Gate Charge (Typ.36nC)
- Improved dv/dt Capability
- 100% Avalanche Tested





Symbol	Parameter		Value	Unit
V <sub>DSS</sub>	Drain to Source Voltage		400	V
۱ <sub>D</sub>	Continuous Drain Current (@T <sub>c</sub> =25 °C)		10	А
	Continuous Drain Current (@T <sub>c</sub> =100 °C)		6.2	А
I <sub>DM</sub>	Drain current pulsed	(note 1)	40	A
V <sub>GS</sub>	Gate to Source Voltage		±30	V
E <sub>AS</sub>	Single pulsed Avalanche Energy	(note 2)	952	mJ
E <sub>AR</sub>	Repetitive Avalanche Energy	(note 1)	12.5	mJ
dv/dt	Peak diode Recovery dv/dt	(note 3)	5.0	V/ns
P <sub>D</sub>	Total power dissipation (@T <sub>c</sub> =25 °C)		125	W
	Derating Factor above 25°C		1.0	W/ºC
T <sub>STG</sub> , T <sub>J</sub>	Operating Junction Temperature & Storage Temperature		-55 ~ + 150	°C
TL	Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds.		300	°C

#### **THERMAL CHARACTERISTICS**

Symbol	Parameter	Value	Unit
R <sub>thjc</sub>	Thermal resistance, Junction to case	1.0	°C/W
R <sub>thja</sub>	Thermal resistance, Junction to ambient	62.5	2, •••

### ABSOLUTE MAXIMUM RATINGS

#### IRF740

## **ELECTRICAL CHARACTERISTIC** ( $T_c = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Off charact	eristics					
BV <sub>DSS</sub>	Drain to source breakdown voltage	Vgs=0V,Id=250uA	400	-	-	V
I <sub>DSS</sub>	Drain to source leakage current	VDS=250V,VGS=0V	-	-	1	uA
		VDs=200V,Tc=125°C	-	-	50	uA
I <sub>GSS</sub>	Gate to source leakage current, forward	VDS=30V,VGS=0V	-	-	100	nA
	Gate to source leakage current, reverse	VDS=-30V,VGS=0V	-	-	-100	nA
On characte	eristics					
V <sub>GS(TH)</sub>	Gate threshold voltage	Vds=Vgs,Id=250uA	2.0	-	4.0	V
R <sub>DS(ON)</sub>	Drain to source on state resistance	VGS=10V,ID=5.0A		0.46	0.55	Ω
Dynamic ch	aracteristics					
C <sub>iss</sub>	Input capacitance	VGS=0V,VDS=25V,f=1MHz	-	1450	1800	pF
C <sub>oss</sub>	Output capacitance		-	145	200	
C <sub>rss</sub>	Reverse transfer capacitance		-	35	45	
t <sub>d(on)</sub>	Turn on delay time		-	30	50	- ns
tr	Rising time	VDS=200V,ID=10A,RG=250hm (note 4,5)	-	60	150	
t <sub>d(off)</sub>	Turn off delay time		-	150	300	
t <sub>f</sub>	Fall time		-	60	150	
Qg	Total gate charge		-	36	60	nC
$Q_{gs}$	Gate -source charge	VDS=320V,VGS=10V,ID=10A (note 4,5)	-	6.0	-	
Q <sub>gd</sub>	Gate -drain charge		-	14	-	

#### SOURCE TO DRAIN DIODE RATINGS CHARACTERISTICS

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
١ <sub>s</sub>	Continuous source current	Integral reverse p-n Junction	-	-	10	А
I <sub>SM</sub>	Pulsed source current	diode in the MOSFET	-	-	40	А
V <sub>SD</sub>	Diode forward voltage drop.	Is=10A, VGs=0V	-	-	1.2	V
T <sub>rr</sub>	Reverse recovery time	Is=10A, Vgs=0V dIF/dt=100A/us	-	335	-	ns
Q <sub>rr</sub>	Breakdown voltage temperature		-	3.6	-	nC

#### Notes

2. L = 18.5mH, IAs=10A, VDD= 50V, Rg=50 $\Omega$ , Starting TJ= 25°C

3.  $Isd \le 10A$ , di/dt = 300A/us,  $Vdd \le BVdss$ ,  $Staring TJ=25^{\circ}C$ 

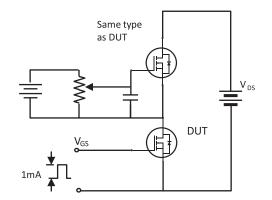
4. Pulse Test : Pulse Width  $\leq$  300us, duty cycle  $\leq$  2%

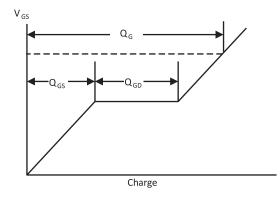
5. Essentially independent of operating temperature.

<sup>1.</sup> Repeatitive rating : pulse width limited by junction temperature.

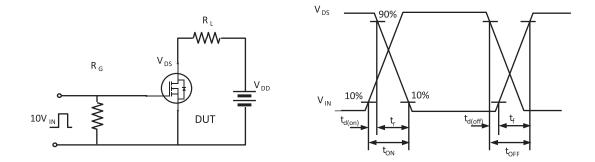
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### Fig. 1. Gate charge test circuit & waveform

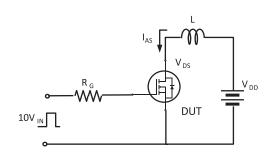


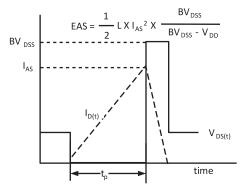


### Fig. 2. Switching time test circuit & waveform



#### Fig. 3. Unclamped Inductive switching test circuit & waveform

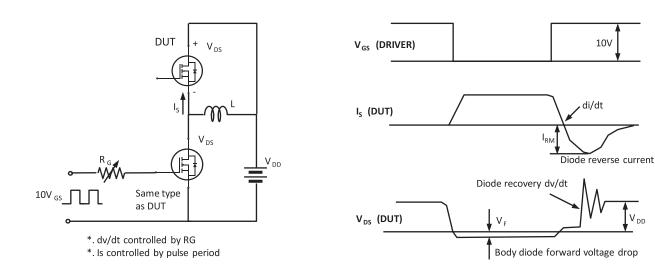




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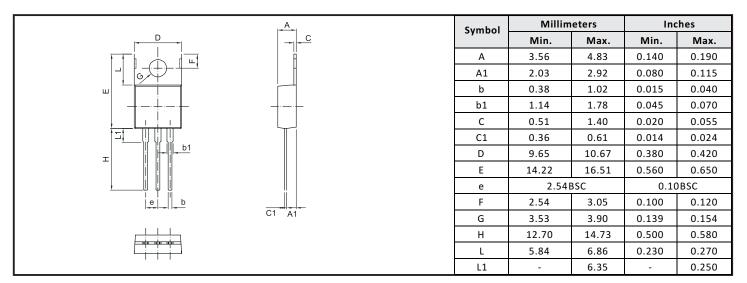
 $V_{DD}$ 

### Fig. 4. Peak diode recovery dv/dt test circuit & waveform



#### **PACKAGE DIMENSIONS**

#### **TO-220AB**



## 5EMIWILL

### **CONTACT US**

#### Headquarters

A Building Caohejing I&E Park Pujiang Minhang Shanghai China

Web http://www.semiwill.com

**By Telephone** General: 86-21-34637654 Sales: 86-21-34637458 Customer Service: 86-21-34637172

**By Email** Sales: sales@semiwill.com Customer Service: cs@semiwill.com Technical Support: fae@semiwill.com

**By Fax** General: 86-21-34637173 Sales:86-21-39650654

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